

U RESIN 705QF



U RESIN 705QF is a Fine paste abrasion resistant ceramic filled rebuild putty that can be used to protect new or worn components to extend life under abrasive and erosive conditions.

U RESIN 705QF is a two component, 100% solids epoxy composite comprising of specially graded hardened ceramics combined with an epoxy resin base that provides extra adhesive and mechanical strength.

PROFILE:

	PART A	PART B	MIXED
Colour			GREY
Mix Ration (by Weight)	100	50	
Pot Life @ 25°C (mins)			25
Coverage per m2 @ 10mm			18kg
Cure Time @ 25°C (hours)			6
Ultimate Time @ 25°C (hours)			24

SURFACE PREPARATION

The surface should be free of all foreign matter such as dirt, oil, loose particles, rust and other contaminates.

The substrate surface should be abraded by hand or mechanical methods of preparation such as grinding, scarifying, abrasive blasting and the like to obtain a good surface profile of 70-75 micron finish for bonding.

MIXING AND APPLICATION INFORMATION

U RESIN 705QF is a two pack 100% solids epoxy system, which has a putty consistency when mixed. This enables the mixed material to be applied up to 30mm depth on vertical application. The two components should be placed on a mixing board and mixed using a spatula or trowel until a uniform consistency is obtained.

The mixed epoxy is now applied using a trowel or spatula. Apply a little water to obtain a smooth finish with the final application. Differences in cure time will arise due to volume of material mixed, thickness of application and ambient temperatures.

TYPICAL APPLICATIONS

Pumps, Pipes, Shafts, Valves, Hoppers, Cones & Wear Plate Grouting

FEATURES

- Excellent Abrasion Resistance
- Free of all Solvents
- Easy to Apply
- High Mechanical Strength
- Rated Non DG for Transport

The information contained herein is true and accurate, based on laboratory conditions. It is recommended that the user contact the manufacturer to confirm suitability as field conditions may vary and yield different results. Testing of this product is strongly recommended to confirm suitability for specific applications. Data should not be used for specification purposes.